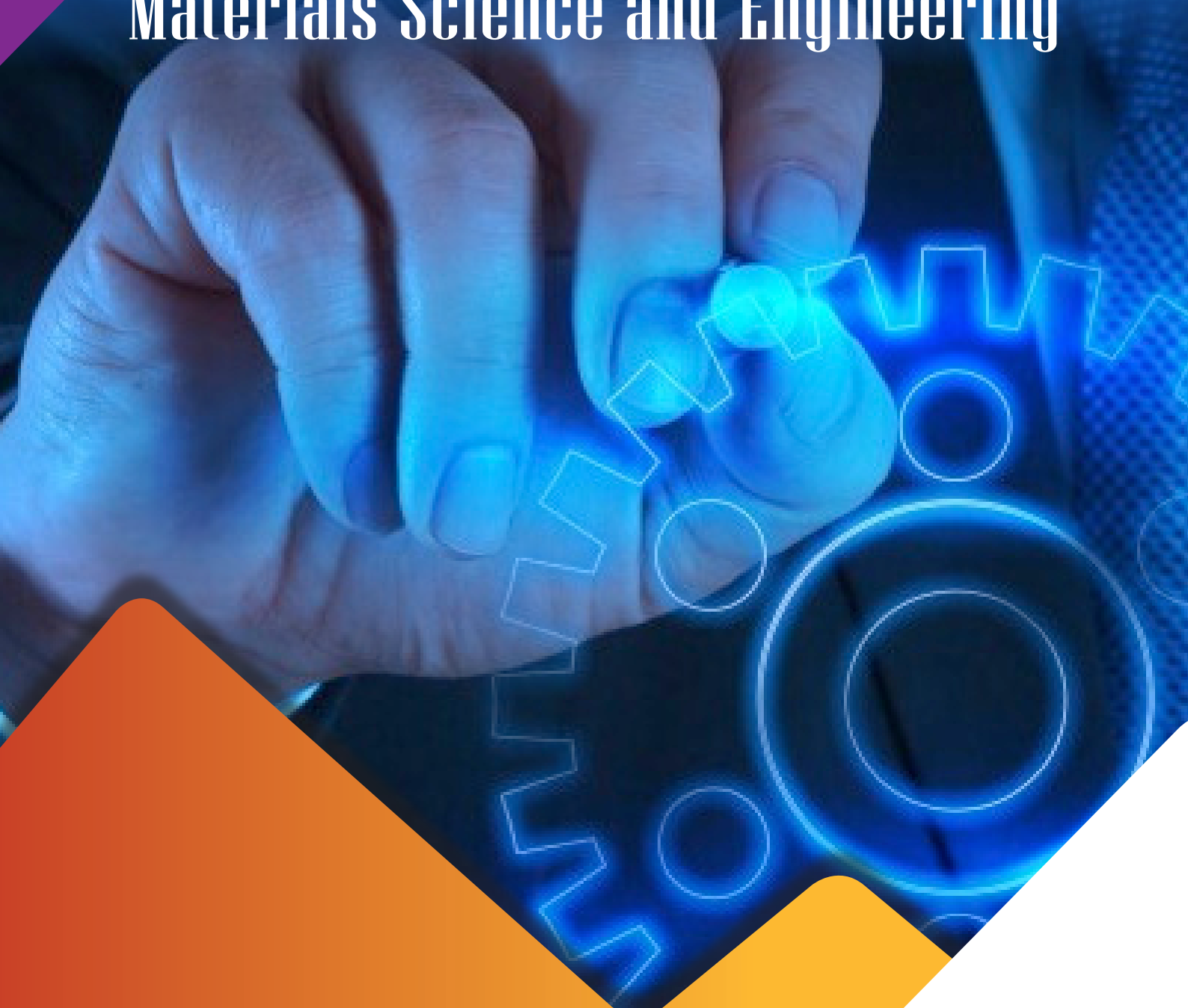


Announcement

conferenceseries.com

8th International Conference and Exhibition on
Materials Science and Engineering



Osaka, Japan

Monday, May 29-Wednesday, May 31, 2017

<http://materialsscience.conferenceseries.com/asia-pacific/>

**MatScience
2017**

Dear Colleagues,

Conference Series Ltd is delighted to welcome you to Osaka, Japan for the prestigious **8th International Conference and Exhibition on Materials Science and Engineering. MatScience 2017** will focus on the theme “Modernization of Materials Science and Engineering”. We are confident that you will enjoy the Scientific Program of this upcoming Conference.

We look forward to see you at Osaka, Japan.

With Regards,

MatScience 2017 Operating Committee

Conference Series Ltd Conferences

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**MatScience
2017**

Program Announcement

Accommodation

A large number of rooms have been reserved. Discounted room rates for MatScience 2017 participants are proposed. Only reservations made through the Conference will benefit these rates. The Congress Center can be easily reached by Public transportation.

Exhibition and Sponsorship

An Exhibition will be held concurrently with the Conference. The coffee break and lunch areas will be located adjacent to the booths. Thanks to exhibitors from all over the world, attendees will have a complete overview of new findings in the fields of Material Science.

About Osaka

Osaka is the second largest metropolitan area in Japan and serves a major economic hub. Historically a merchant city, Osaka has also been known as the "Nation's Kitchen". With a population of 2.5 million, Osaka is Japan's third largest and second most important city. It has been the economic powerhouse of the Kansai region for many centuries. The city's west side has the main port as well as a tourist destination with attractions such as Kyocera Dome, Universal Studios Japan, Osaka aquarium, Minami, Osaka castle, Umeda sky building and the Tempozan Harbour Village. Osaka is known for its food, both in Japan and abroad. Author Michael Booth and food critic François Simon of Le Figaro have both suggested that Osaka is the food capital of the world. Osaka's culinary prevalence is the result of a location that has provided access to high quality ingredients, a high population of merchants, and close proximity to the ocean and waterway trade. In recent years, Osaka has started to garner more attention from foreigners with the increased popularity of cooking and dining in popular culture. The National Museum of Art (NMAO) is a subterranean Japanese and international art museum, housing mainly collections from the post-war era and regularly welcoming temporary exhibitions. Osaka Science Museum is in a five storied building next to the National Museum of Art, with a planetarium and an OMNIMAX theatre. The Museum of Oriental Ceramics holds more than 2,000 pieces of ceramics, from China, Korea, Japan and Vietnam, featuring displays of some of their Korean celadon under natural light.

Venue

Osaka, Japan

Important Dates

Abstract submission opens: September 05, 2016

Registration opens: September 12, 2016

Early bird registration: March 27, 2017

On spot registration: May 29, 2017

Conference Secretariat

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MatScience 2017